Surface Finishing

- Infra-red dipping – track and pads are covered by Sn/Pb
- Hot air leveling (HAL) – only uncovering by soldermask areas are covered with Sn/Pb - 0.0005~0.035mm (20 micro in. ~ 1400 micro in.)
- Lead-free hot air leveling – 2~50microns
- Passivation (OSP – organical film for protection of copper) – 0,03~0,05microns
- Galvanic Nickel/Gold over edge connectors – Nickel ~5microns, Gold ~1micron